DS50EV401 2.5 Gbps / 5.0 Gbps or 8.0 Gbps Quad Cable and Backplane Equalizer

Check for Samples: DS50EV401

FEATURES

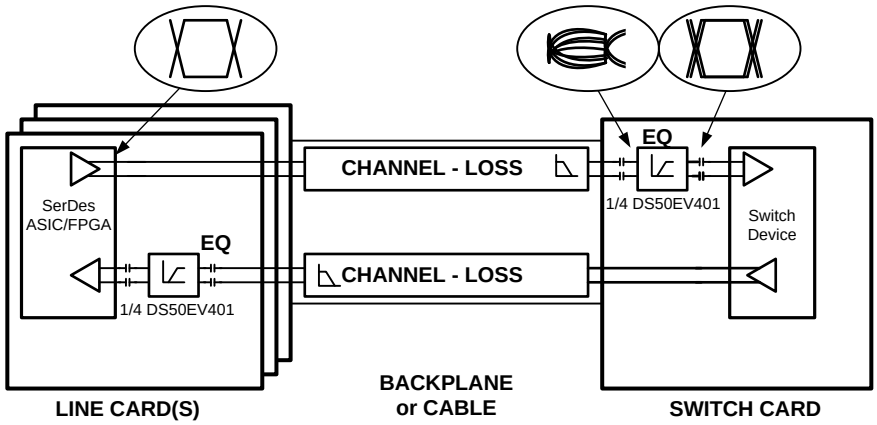
- **Automatic power management on an individual lane basis**
- **Data rate optimized equalization**
- **Operates over 7 meter of 24 AWG Twin-ax Cables up to 8 Gbps**
- **Typical residual deterministic jitter:**
- **0.18 UI @ 8 Gbps w/ 30” of FR4**
- **0.18 UI @ 5 Gbps w/ 40” of FR4**
- **0.16 UI @ 2.5 Gbps w/ 40” of FR4**
- **8 kV HBM ESD protection**
- **-40 to 85°C operating temperature range**
- **7 mm x 7 mm 48-pin leadless WQFN package**
- **Single power supply of either 3.3V or 2.5V**
- **Low power (typically 95 mW per channel at 2.5V V_{DD})**

DESCRIPTION

The DS50EV401 is a low power, programmable equalizer specifically designed to reduce inter-symbol interference (ISI) induced by a variety of interconnect media. In all modes, the equalizer can operate, error free, with an input eye that is completely closed by interconnect ISI. The MODE control, allows the user to select between equalization settings for 8.0 Gbps operation or 2.5 Gbps / 5.0 Gbps operation.

The DS50EV401 uses Current-mode logic (CML) on both input and output ports, which provide constant 50 ohm single-ended impedance to AC ground. Differential signaling is implemented through out the entire signal path to minimize supply induced jitter. The DS50EV401 is available in a 7mm x 7mm 48-pin leadless WQFN package, and is powered from a single power supply of either 3.3 or 2.5V.

Application Diagram



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PIN DESCRIPTIONS

Pin Name	Pin Number	I/O, Type	Description
HIGH SPEED DIFFERENTIAL I/O			
IN_0+ IN_0-	1 2	I, CML	Inverting and non-inverting CML differential inputs to the equalizer. An on-chip 50Ω terminating resistor connects IN_0+ to VDD and IN_0- to VDD.
IN_1+ IN_1-	4 5	I, CML	Inverting and non-inverting CML differential inputs to the equalizer. An on-chip 50Ω terminating resistor connects IN_1+ to VDD and IN_1- to VDD.
IN_2+ IN_2-	8 9	I, CML	Inverting and non-inverting CML differential inputs to the equalizer. An on-chip 50Ω terminating resistor connects IN_2+ to VDD and IN_2- to VDD.
IN_3+ IN_3-	11 12	I, CML	Inverting and non-inverting CML differential inputs to the equalizer. An on-chip 50Ω terminating resistor connects IN_3+ to VDD and IN_3- to VDD.
OUT_0+ OUT_0-	36 35	O, CML	Inverting and non-inverting CML differential outputs from the equalizer. An on-chip 50Ω terminating resistor connects OUT_0+ to V_{DD} and OUT_0- to V_{DD}.
OUT_1+ OUT_1-	33 32	O, CML	Inverting and non-inverting CML differential outputs from the equalizer. An on-chip 50Ω terminating resistor connects OUT_1+ to V_{DD} and OUT_1- to V_{DD}.
OUT_2+ OUT_2-	29 28	O, CML	Inverting and non-inverting CML differential outputs from the equalizer. An on-chip 50Ω terminating resistor connects OUT_2+ to V_{DD} and OUT_2- to V_{DD}.
OUT_3+ OUT_3-	26 25	O, CML	Inverting and non-inverting CML differential outputs from the equalizer. An on-chip 50Ω terminating resistor connects OUT_3+ to V_{DD} and OUT_3- to V_{DD}.
EQUALIZATION CONTROL			
MODE	14	I, LVCMOS	MODE selects the equalizer frequency for EQ channels. MODE is internally pulled low. L = 6.0 - 8.0 Gbps setting H = 2.5 Gbps / 5.0 Gbps setting
DEVICE CONTROL			
EN0	44	I, LVCMOS	Channel 0 Enable Input Pin H = normal operation (enabled) L = standby mode Pin is internally pulled High.
EN1	42	I, LVCMOS	Channel 1 Enable Input Pin H = normal operation (enabled) L = standby mode Pin is internally pulled High.
EN2	40	I, LVCMOS	Channel 2 Enable Input Pin H = normal operation (enabled) L = standby mode Pin is internally pulled High.
EN3	38	I, LVCMOS	Channel 3 Enable Input Pin H = normal operation (enabled) L = standby mode Pin is internally pulled High.
SD0	45	O, LVCMOS	Channel 0 Signal Detect Output Pin H = signal detected L = no signal detected
SD1	43	O, LVCMOS	Channel 1 Signal Detect Output Pin H = signal detected L = no signal detected
SD2	41	O, LVCMOS	Channel 2 Signal Detect Output Pin H = signal detected L = no signal detected.
SD3	39	O, LVCMOS	Channel 3 Signal Detect Output Pin H = signal detected L = no signal detected
POWER			
V_{DD}	3, 6, 7, 10, 13, 15, 46	Power	V_{DD} = 2.5V ± 5% or 3.3V ± 10%. V_{DD} pins should be tied to V_{DD} plane through low inductance path. A 0.1µF bypass capacitor should be connected between each V_{DD} pin to GND planes.
GND	22, 24, 27, 30, 31, 34	Ground	Ground reference. GND should be tied to a solid ground plane through a low impedance path.
Exposed Pad	DAP	Ground	Ground reference. The exposed pad at the center of the package must be connected to ground plane of the board.

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PIN DESCRIPTIONS (continued)

Pin Name	Pin Number	I/O, Type	Description
OTHER			
Reserv	16, 17, 18, 19, 20, 21, 23, 37, 47, 48		Reserved. Do not connect. Leave open.

Connection Diagram

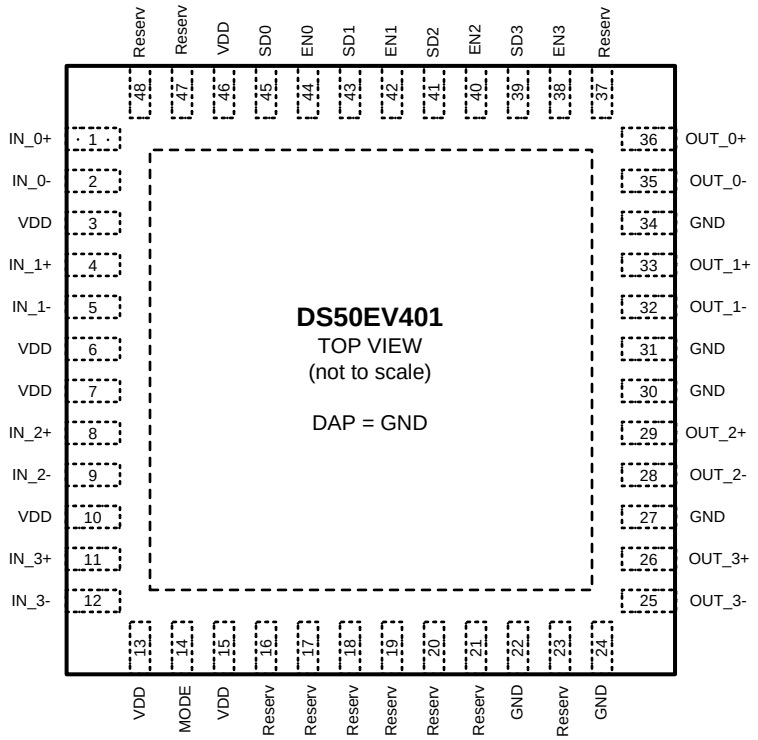


Figure 1. TOP VIEW — Not to scale

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

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Absolute Maximum Ratings (1)(2)

Supply Voltage (V_{DD})	-0.5V to +4.0V
LVCMOS Input Voltage	-0.5V + 4.0V
LVCMOS Output Voltage	-0.5V to 4.0V
CML Input/Output Voltage	-0.5V to 4.0V
Junction Temperature	+150°C
Storage Temperature	-65°C to +150°C
ESD Rating	
HBM, 1.5 kΩ, 100 pF	>8 kV
Thermal Resistance θ_{JA}, No Airflow	30°C/W

(1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions indicate conditions at which the device is functional and the device should not be operated beyond such conditions. Absolute Maximum Numbers are specified for a junction temperature range of -40°C to +125°C. Models are validated to Maximum Operating Voltages only.

(2) **If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office / Distributors for availability and specifications.**

Recommended Operating Conditions

	Min	Typ	Max	Units
Supply Voltage				
V_{DD} to GND, or	2.375	2.5	2.625	V
V_{DD} to GND	3.0	3.3	3.6	V
Ambient Temperature	-40	25	+85	°C

Electrical Characteristics

Over recommended operating supply and temperature ranges with default register settings unless other specified. (1) (2)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
POWER						
PD	Power Dissipation 3.3V Operation	Signal active, V_{DD} = 3.3V, 3.6V		510	700	mW
		No signal, V_{DD} = 3.3V, 3.6V			100	mW
PD	Power Dissipation 2.5V Operation	Signal active, V_{DD} = 2.5V, 2.625V		380	490	mW
		No signal, V_{DD} = 2.5V, 2.625V		30		mW
N	Supply Noise Tolerance (3)	Up to 50 MHz		100		mV_{P-P}
LVCMOS / LVTTL DC SPECIFICATIONS						
V_{IH}	High Level Input Voltage	3.3V Operation	2.0		V_{DD}	V
		2.5V Operation	1.6		V_{DD}	V
V_{IL}	Low Level Input Voltage		-0.3		0.8	V
V_{OH}	High Level Output Voltage	I_{OH} = -3mA, 3.3V Operation	2.4			V
		I_{OH} = -3mA, 2.5V Operation	2.0			V
V_{OL}	Low Level Output Voltage	I_{OL} = 3mA			0.4	V
I_{IH}	Input High Current	V_{IN} = V_{DD}, MODE pin (pull down)			+140	µA
		V_{IN} = V_{DD}, EN pins (pull up)	-15		+15	µA
I_{IL}	Input Low Current	V_{IN} = 0V, MODE pin (pull down)	-15		+15	µA
		V_{IN} = 0V, EN pins (pull up)	-40			µA

(1) Typical values represent most likely parametric norms at V_{DD} = 3.3V or 2.5V, T_A = 25°C., and at the Recommended Operation Conditions at the time of product characterization and are not ensured.

(2) The Electrical Characteristics tables list ensured specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not ensured.

(3) Allowed supply noise (mV_{P-P} sine wave) under typical conditions.

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Electrical Characteristics (continued)

Over recommended operating supply and temperature ranges with default register settings unless other specified. (1) (2)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
CML RECEIVER INPUTS (IN_n+, IN_n-)						
V_{TX}	Input Voltage Swing (Launch Amplitude)	Measured at point A, AC or DC coupled, Figure 2	400	1000	1600	mV_{P-P}
V_{IN-S}	Input Voltage Sensitivity	AC-Coupled or DC-Coupled Required Differential Envelope measured at point B, Figure 2, (4), See FR4 / BACKPLANE Typical Performance Eye Diagrams,		170		mV_{P-P}
R_{LI}	Differential Input Return Loss	100 MHz – 4.0 GHz, with fixture's effect de-embedded		10		dB
R_{IN}	Input Resistance	Single ended to V_{DD}	40	50	60	Ω
CML OUTPUTS (OUT_n+, OUT_n-)						
V_O	Output Voltage Swing	Differential measurement with OUT_n+ and OUT_n- terminated by 50Ω to GND AC-Coupled, Figure 3	800	1000	1200	mV_{P-P}
V_{OCM}	Output Common-Mode Voltage	Single-ended measurement DC-Coupled with 50Ω termination, (5)		V_{DD} – 0.25		V
t_R, t_F	Transition Time	20% to 80% of differential output voltage, measured within 1" from output pins, Figure 3, (5)		40		ps
R_O	Output Resistance	Single-ended to V_{DD}	40	50	60	Ω
R_{LO}	Differential Output Return Loss	100 MHz – 4.0 GHz, with fixture's effect de-embedded. IN_n+ = static high		10		dB
t_{PLHD}	Differential Low to High Propagation Delay	Propagation delay measurement at 50% V_O between input to output, 100 Mbps, Figure 4, (6)		240		ps
t_{PHLD}	Differential High to Low Propagation Delay			240		ps
t_{ID}	Idle to Valid Differential Data	VIN = 800 mVp-p, 5 Gbps, EIEOS, 40" of 6 mil microstrip FR4, Figure 5, (7)		8		ns
t_{DI}	Valid Differential data to idle	VIN = 800 mVp-p, 5 Gbps, EIOS, 40" of 6 mil microstrip FR4, Figure 5, (7)		8		ns
t_{CCSK}	Inter Pair Channel to Channel Skew	Difference in 50% crossing between channels		7		ps
EQUALIZATION						
DJ1	Residual Deterministic Jitter at 8 Gbps	30" of 6 mil microstrip FR4, MODE=0, PRBS-7 (2^7-1) pattern, (7) (8)		0.18		UI_{P-P}
DJ2	Residual Deterministic Jitter at 5 Gbps	40" of 6 mil microstrip FR4, MODE=1, PRBS-7 (2^7-1) pattern, (7) (8)		0.18	0.21	UI_{P-P}
DJ3	Residual Deterministic Jitter at 2.5 Gbps	40" of 6 mil microstrip FR4, MODE=1, PRBS-7 (2^7-1) pattern, (7) (8)		0.16	0.18	UI_{P-P}
RJ	Random Jitter	(6) (9)		0.5		psrms

(4) V_{IN-S} is a measurement of the input differential envelope, see FR4 / BACKPLANE Typical Performance Eye Diagrams. The device does not require an open eye.
(5) Specification is ensured by characterization at optimal MODE setting and is not tested in production.
(6) Measured with clock-like {11111 00000} pattern.
(7) Specification is ensured by characterization at optimal MODE setting and is not tested in production.
(8) Deterministic jitter is measured at the differential outputs (point C of Figure 2), minus the deterministic jitter before the test channel (point A of Figure 2). Random jitter is removed through the use of averaging or similar means.
(9) Random jitter contributed by the equalizer is defined as sqrt ($J_{OUT}^2 - J_{IN}^2$). J_{OUT} is the random jitter at equalizer outputs in ps-rms, see point C of Figure 2; J_{IN} is the random jitter at the input of the equalizer in ps-rms, see point B of Figure 2.

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TIMING DIAGRAMS

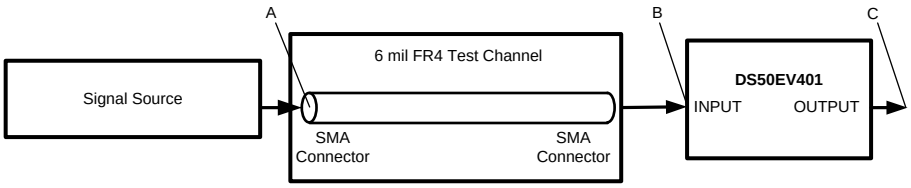


Figure 2. Test Setup Diagram

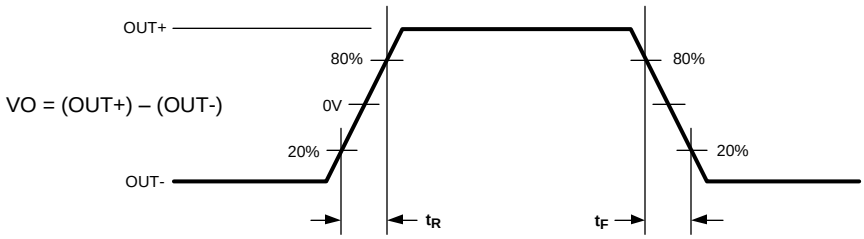


Figure 3. CML Output Transition Times

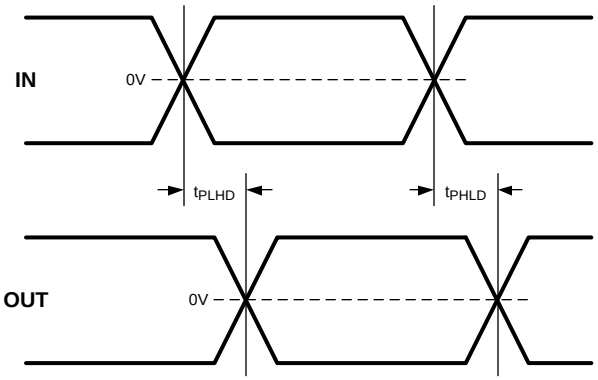


Figure 4. Propagation Delay Timing Diagram

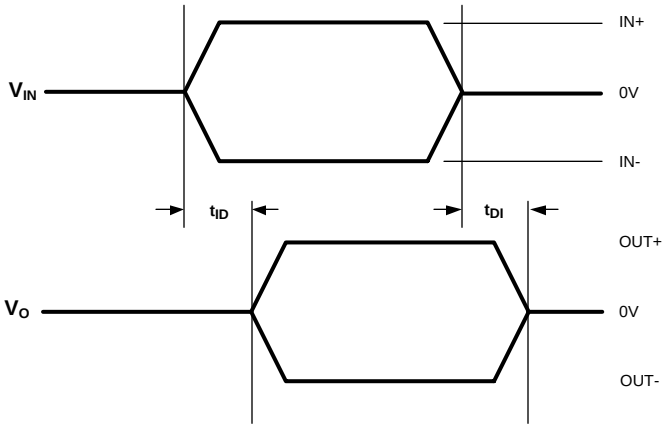


Figure 5. Idle Timing Diagram

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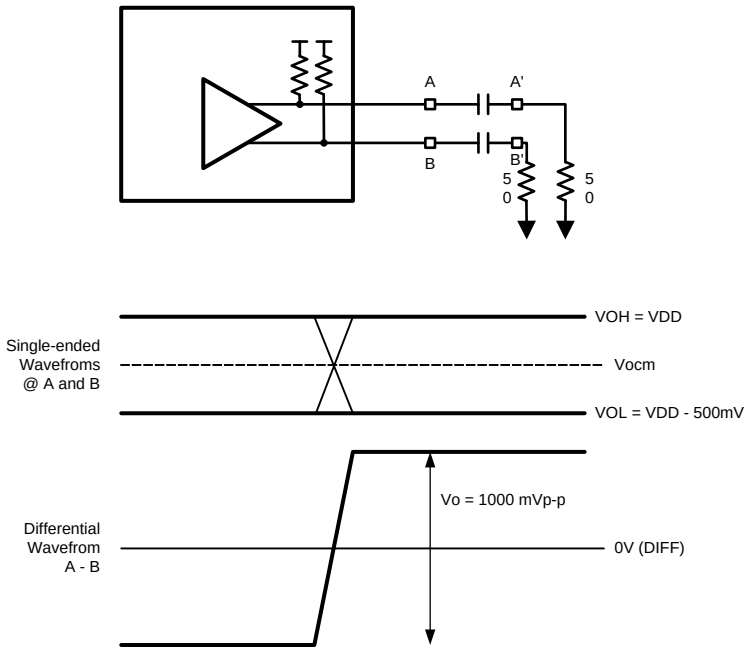


Figure 6. CML Output Swings at A/B

FUNCTIONAL DESCRIPTION

DS50EV401 APPLICATIONS INFORMATION

The DS50EV401 is a programmable quad equalizer optimized for copper backplanes and cables at transmission rates of 2.5 Gbps up to 8 Gbps. The device consists of an input receive equalizer followed by a limiting amplifier. The equalizer is designed to open an input eye that is completely closed due to inter-symbol interference (ISI) induced by the channel interconnect. The equalization is set to keep residual deterministic jitter below 0.2 unit intervals (UI) regardless of data rate. This equalization scheme allows one equalization setting to satisfy most serial links between 2.5 and 5.0 Gbps. The DS50EV401 is intended as a unidirectional receiver that should be placed in close physical proximity to the link end point. Therefore the transmitter does not include de-emphasis as TX equalization would not be needed over the short distance between the equalizer and the end point.

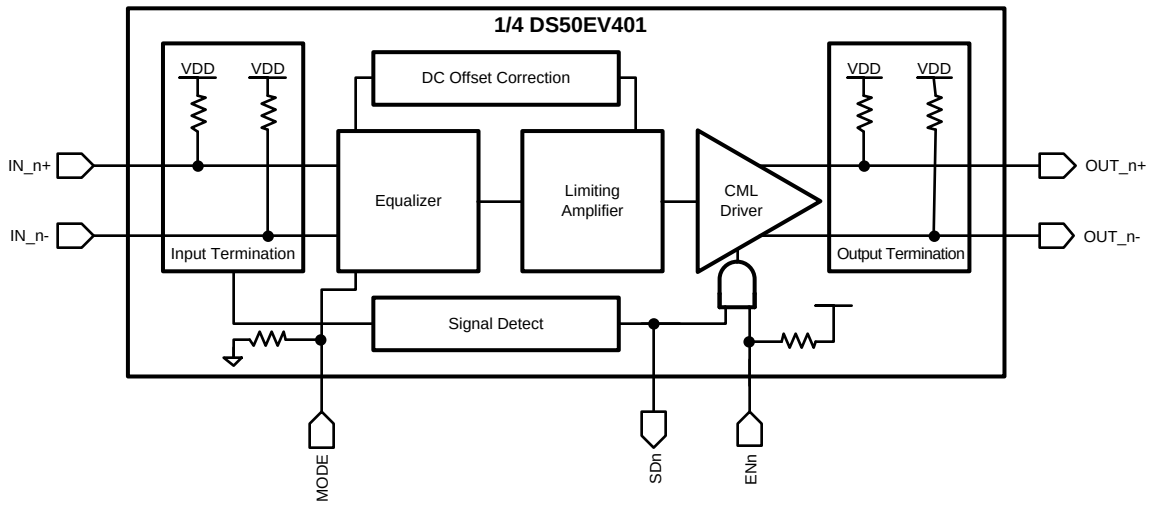


Figure 7. General Block Diagram

Data Channels

The DS50EV401 consists of four data channels. Each channel provides input termination, receiver equalization, signal limiting, offset cancellation, and a CML output driver, as shown in Figure 7. The data channels support two levels of equalization, controlled by the pin MODE. The equalization levels are set simultaneously on all 4 channels, as described in Table 1.

When an idle condition is sensed on a channel's input, the transmit driver is automatically placed into electrical idle mode. The common mode voltage is set, and the differential output is forced to zero. To save power, the output driver current is powered off when the device is in electrical idle mode. All other circuits maintain their bias currents allowing a fast recovery from idle to the active state. Electric idle is performed on a per channel basis, and several channels can be in idle while others are actively passing data.

Table 1. MODE Control Table

6 mil microstrip FR4 trace length (in)	24 AWG Twin-AX cable length (m)	Frequency	Channel Loss	MODE
0–30	0–7	8 Gbps	16 dB	0
0–40	0–10	2.5 Gbps 5.0 Gbps	14 dB 20 dB	1

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APPLICATION INFORMATION

GENERAL RECOMMENDATIONS

The DS50EV401 is a high performance device capable of delivering excellent performance. As with most CML devices, it is recommended that AC coupling capacitors be used to ensure I/O compatibility with other devices. In order to extract full performance from the device in a particular application, good high-speed design practices must be followed. TI's LVDS Owner's Manual (literature number SNLA187), provides detailed information about managing signal integrity and power delivery to get the most from your design.

PCB LAYOUT CONSIDERATIONS FOR DIFFERENTIAL PAIRS

The CML inputs and outputs must have a controlled differential impedance of 100Ω. It is preferable to route CML lines exclusively on one layer of the board, particularly for the input traces. The use of vias should be avoided if possible. If vias must be used, they should be used sparingly and must be placed symmetrically for each side of a given differential pair. Route the CML signals away from other signals and noise sources on the printed circuit board. See AN-1187 (SNOA401) for additional information on WQFN packages.

PACKAGE FOOTPRINT / SOLDERING

See Application Note number 1187, "Leadless Leadframe Package" for information on PCB footprint and soldering recommendations.

POWER SUPPLY BYPASSING

Two approaches are recommended to ensure that the DS50EV401 is provided with an adequate power supply. First, the supply (V_{DD}) and ground (GND) pins should be connected to power planes routed on adjacent layers of the printed circuit board. The layer thickness of the dielectric should be minimized so that the V_{DD} and GND planes create a low inductance supply with distributed capacitance. Second, careful attention to supply bypassing through the proper use of bypass capacitors is required. A 0.1µF bypass capacitor should be connected to each V_{DD} pin such that the capacitor is placed as close as possible to the DS50EV401. Smaller body size capacitors can help facilitate proper component placement. Additionally, three capacitors with capacitance in the range of 2.2 µF to 10 µF should be incorporated in the power supply bypassing design as well. These capacitors can be either tantalum or an ultra-low ESR ceramic and should be placed as close as possible to the DS50EV401.

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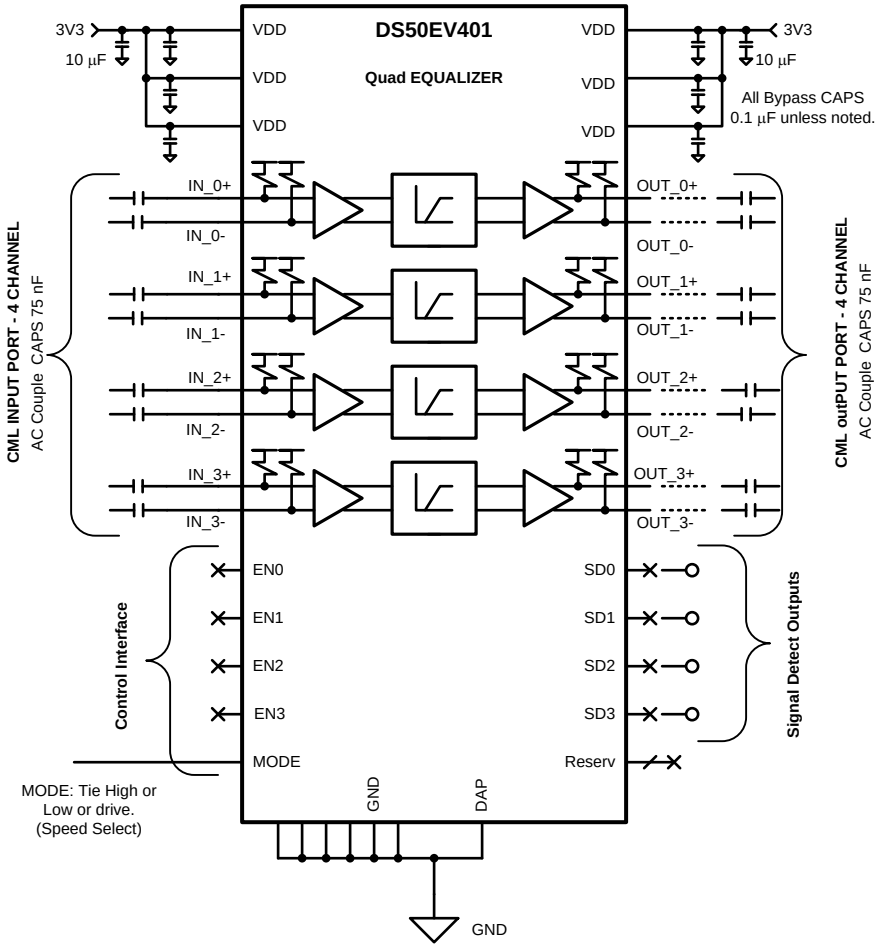


Figure 8. Typical Interface Circuit

The CML inputs are AC coupled to the device as shown in Figure 8. Internal to the device are 50Ω terminations to V_{DD}.

The CML outputs drive 100 Ω transmission lines and are AC coupled and terminated at their load.

The ENABLE inputs and SIGNAL DETECT outputs are optional. Internal to the device the signal detect circuity is connected to the enable circuit providing the automatic power management feature. When the No-signal condition is detected, the respective channel is placed in standby mode. The MODE pin is used to select between low and high data rate equalization settings. Depending upon the application it may be tied High, tied Low, or driven. There are several reserved pins on the device, these are NC pins and should be left open.

Power is supplied through six V_{DD} pins to the device. A 0.1µF capacitor is recommended per pin as close to the device as possible. A larger bulk capacitor is also recommended to be placed near by the device. Ground is supplied to the device via the ground pins and also the DAP.

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TYPICAL PERFORMANCE EYE DIAGRAMS

FR4 / BACKPLANE Typical Performance Eye Diagrams

The plots show the unequalized and equalized eye patterns for various interconnects as noted. Unequalized is shown in the left column and the corresponding equalized eye pattern in shown in the right column.

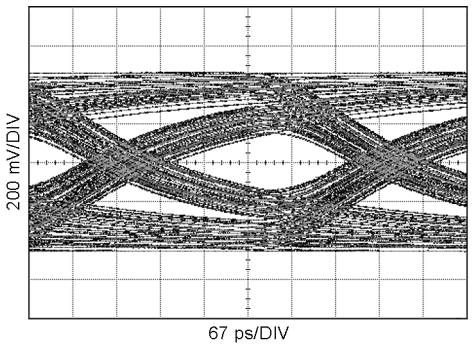


Figure 9. Unequalized Signal (40 in FR4, 2.5 Gbps, PRBS7)

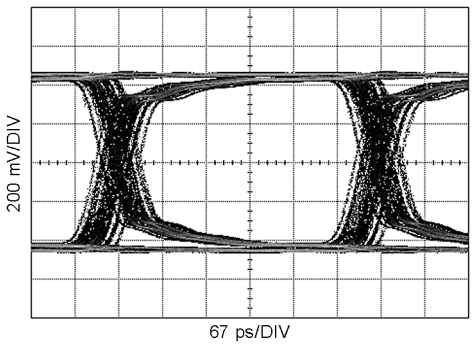


Figure 10. Equalized Signal (40 in FR4, 2.5 Gbps, PRBS7, MODE=1)

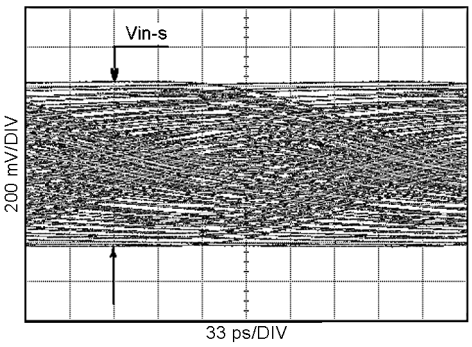


Figure 11. Unequalized Signal (40 in FR4, 5 Gbps, PRBS7)

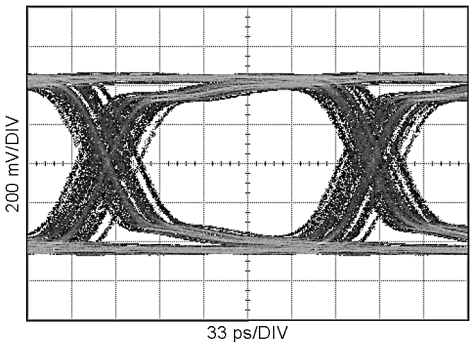


Figure 12. Equalized Signal (40 in FR4, 5 Gbps, PRBS7, MODE=1)

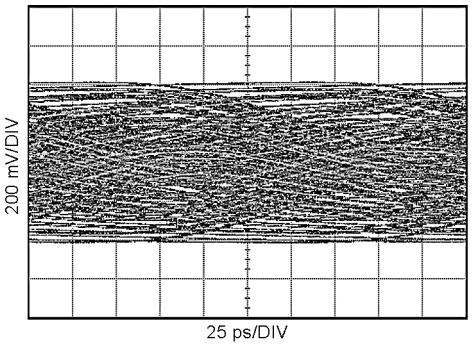


Figure 13. Unequalized Signal (30 in FR4, 8 Gbps, PRBS7)

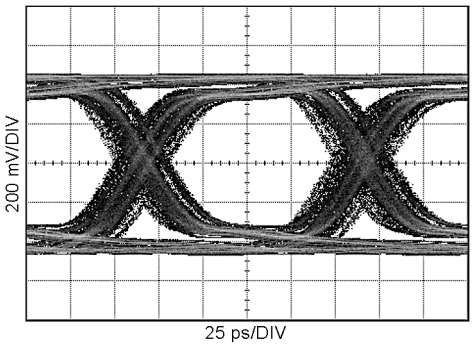


Figure 14. Equalized Signal (30 in FR4, 8 Gbps, PRBS7, MODE=0)

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TYPICAL PERFORMANCE EYE DIAGRAMS (continued)

Twin-AX CABLES Typical Performance Eye Diagrams

The plots show the unequalized and equalized eye patterns for various interconnects as noted. Unequalized is shown in the left column and the corresponding equalized eye pattern in shown in the right column.

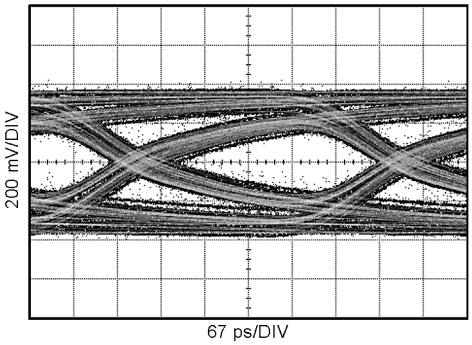


Figure 15. Unequalized Signal (10 m 24 AWG Twin-AX Cable, 2.5 Gbps, PRBS7)

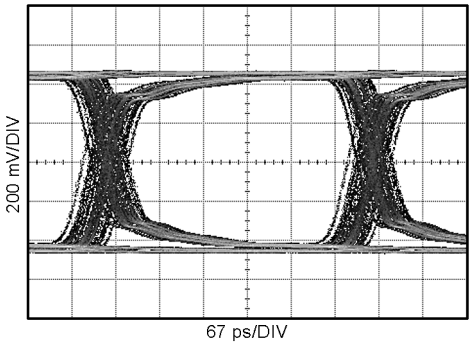


Figure 16. Equalized Signal (10 m 24 AWG Twin-AX Cable, 2.5 Gbps, PRBS7, MODE=1)

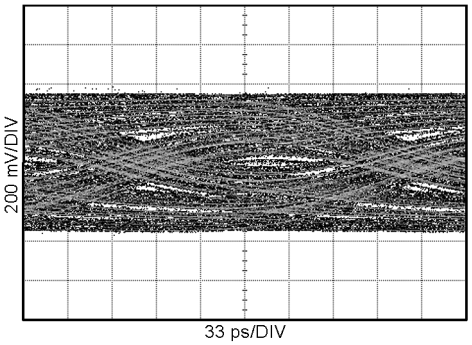


Figure 17. Unequalized Signal (10 m 24 AWG Twin-AX Cable, 5 Gbps, PRBS7)

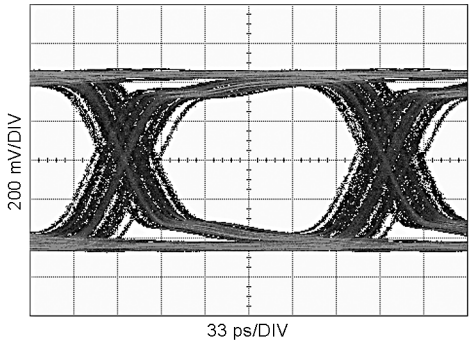


Figure 18. Equalized Signal (10 m 24 AWG Twin-AX Cable, 5 Gbps, PRBS7, MODE=1)

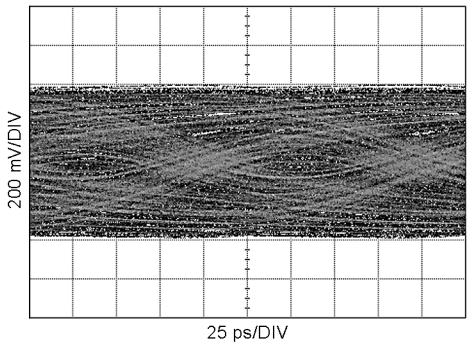


Figure 19. Unequalized Signal (7 m 24 AWG Twin-AX Cable, 8 Gbps, PRBS7)

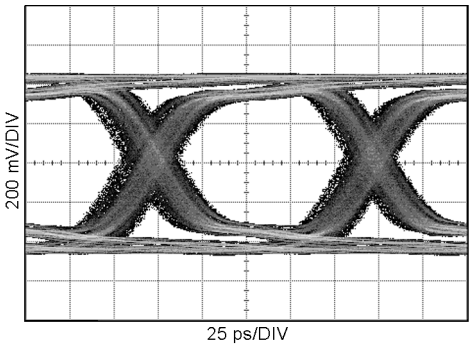


Figure 20. Equalized Signal (7 m 24 AWG Twin-AX Cable, 8 Gbps, PRBS7, MODE=0)

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REVISION HISTORY

Changes from Revision D (March 2013) to Revision E	Page
• Changed layout of National Data Sheet to TI format	12

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
DS50EV401SQE/NOPB	LIFEBUY	WQFN	NJU	48	250	Green (RoHS & no Sb/Br)	CU SN	Level-3-260C-168 HR	-40 to 85	DS50EV401	

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

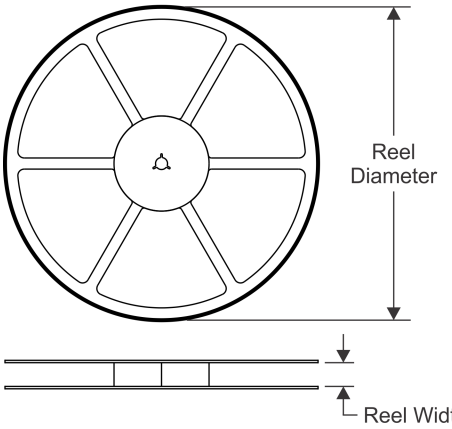
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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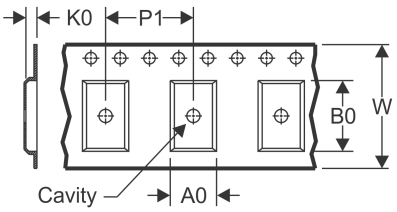
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

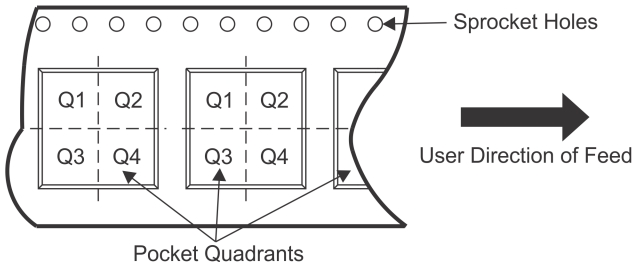


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

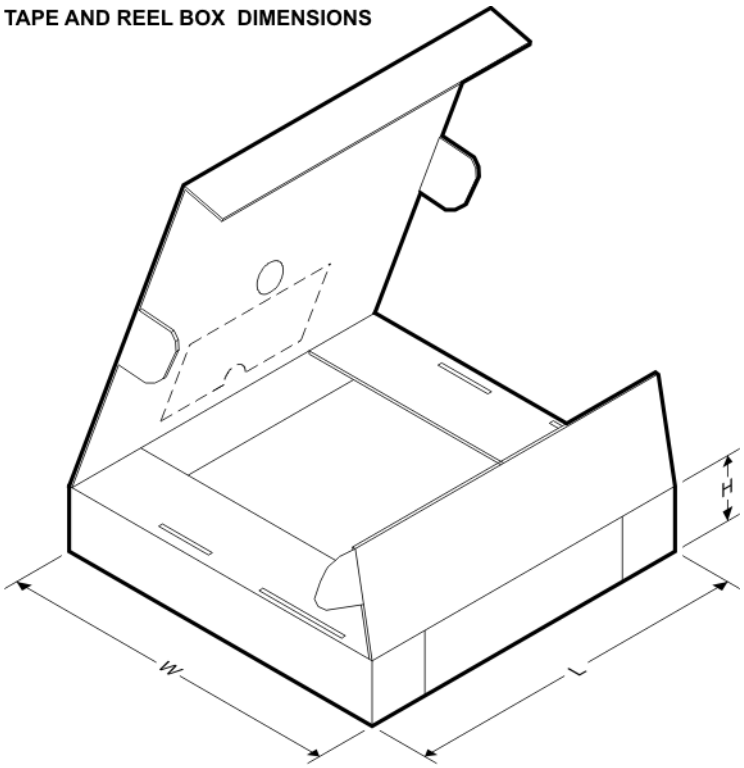
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DS50EV401SQE/NOPB	WQFN	NJU	48	250	178.0	16.4	7.3	7.3	1.3	12.0	16.0	Q1

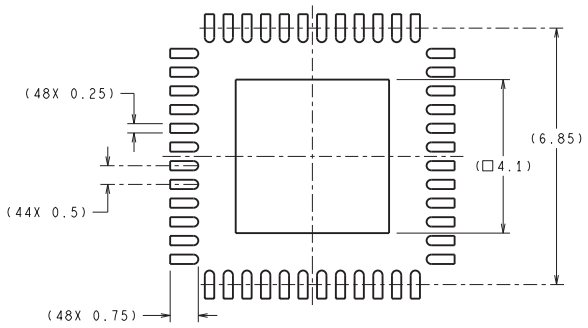
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

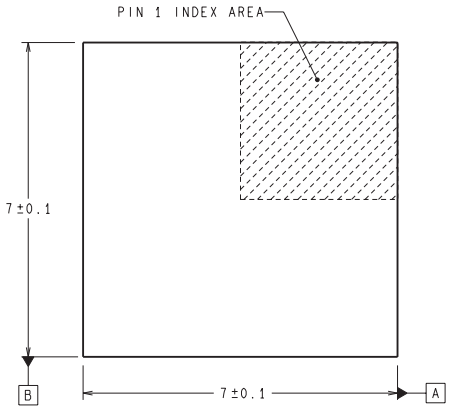
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DS50EV401SQE/NOPB	WQFN	NJU	48	250	210.0	185.0	35.0

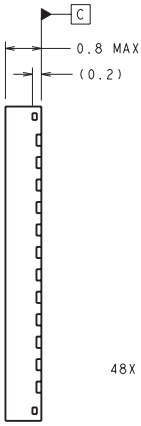
NJU0048D

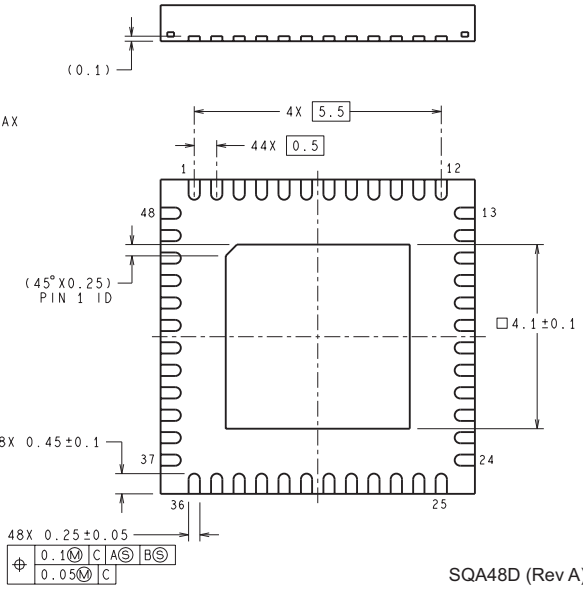


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DIMENSIONS IN ( ) FOR REFERENCE ONLY







SQA48D (Rev A)

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